

ABSTRACT

The wafer supporting device of the present invention comprises a wafer support, disposed within a process chamber in a semiconductor manufacturing apparatus having
5 respective heat sources in upper and lower portions thereof;
a lift member extending from the outside of the support area of the wafer support to the inside and having an inclined upper surface; an arc-shaped lift ring for supporting the lift member; and a lift pin, adapted to vertically move
10 through a through hole in the wafer support, having an upper end part connected to the lift ring; wherein the through hole is covered and substantially closed with the lift ring when the lift pin descends. This eliminates the unevenness in temperature distribution caused by the through hole.

15